

H11AA1

H11AA3

H11AA2

H11AA4

DESCRIPTION

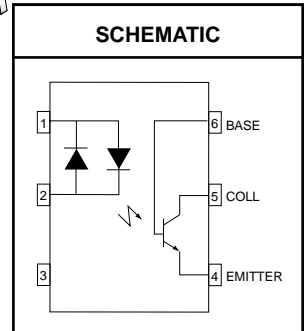
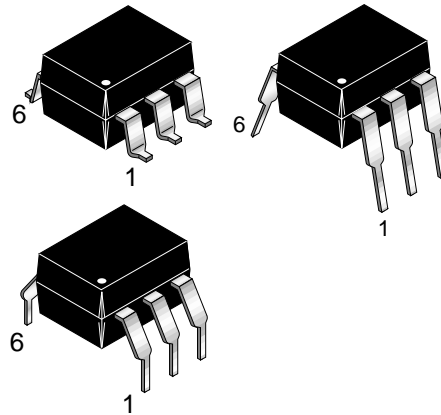
The H11AAX series consists of two gallium-arsenide infrared emitting diodes connected in inverse parallel driving a single silicon phototransistor output.

FEATURES

- Bi-polar emitter input
- Built-in reverse polarity input protection
- Underwriters Laboratory (UL) recognized — File #E90700
- VDE approved — File #E94766 (ordering option '300')

APPLICATIONS

- AC line monitor
- Unknown polarity DC sensor
- Telephone line interface



| Parameter | Symbol | Device | Value | Units |
|---|-----------|--------|----------------|-------|
| TOTAL DEVICE | | | | |
| Storage Temperature | T_{STG} | All | -55 to +150 | °C |
| Operating Temperature | T_{OPR} | All | -55 to +100 | °C |
| Lead Solder Temperature | T_{SOL} | All | 260 for 10 sec | °C |
| Total Device Power Dissipation Derate Linearly From 25°C | P_D | All | 350 | mW |
| | | | 4.6 | mW/°C |
| EMITTER | | | | |
| Continuous Forward Current | I_F | All | 100 | mA |
| Forward Current - Peak (1 μ s pulse, 300 pps) | $I_F(pk)$ | All | ± 1.0 | A |
| LED Power Dissipation Derate Linearly From 25°C | P_D | All | 200 | mW |
| | | | 2.6 | mW/°C |
| DETECTOR | | | | |
| Detector Power Dissipation Derate above 25°C | P_D | All | 300 | mW |
| | | | 4.0 | mW/°C |

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

INDIVIDUAL COMPONENT CHARACTERISTICS

| Parameter | Test Conditions | Symbol | Device | Min | Typ | Max | Unit |
|---|--|------------|----------------------|-----|-----|-----------|------|
| EMITTER | | | | | | | |
| Input Forward Voltage | $I_F = \pm 10 \text{ mA}$ | V_F | All | | 1.2 | 1.5 | V |
| Capacitance | $V_F = 0 \text{ V}, f = 1.0 \text{ MHz}$ | C_J | All | | 80 | | pF |
| DETECTOR | | | | | | | |
| Breakdown Voltage Collector to Emitter | $I_C = 1.0 \text{ mA}, I_F = 0$ | BV_{CEO} | All | 30 | | | V |
| Collector to Base | $I_C = 100 \mu\text{A}, I_F = 0$ | BV_{CBO} | All | 70 | | | V |
| Emitter to Base | $I_E = 100 \mu\text{A}, I_F = 0$ | BV_{EBO} | All | 5 | | | V |
| Emitter to Collector | $I_E = 100 \mu\text{A}, I_F = 0$ | BV_{ECO} | All | 7 | | | V |
| Leakage Current Collector to Emitter | $V_{CE} = 10 \text{ V}, I_F = 0$ | I_{CEO} | H11AA1,3,4 H11AA2 | | | 50 200 | nA |
| Capacitance Collector to Emitter | $V_{CE} = 0, f = 1 \text{ MHz}$ | C_{CE} | All | | 10 | | pF |
| Collector to Base | $V_{CE} = 0, f = 1 \text{ MHz}$ | C_{CB} | All | | 80 | | pF |
| Emitter to Base | $V_{CE} = 0, f = 1 \text{ MHz}$ | C_{EB} | All | | 15 | | pF |

TRANSFER CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

| Characteristics | Test Conditions | Symbol | Device | Min | Typ | Max | Units |
|---|---|---------------|--------|-----|-----|-----|-------|
| Current Transfer Ratio, Collector to Emitter | $I_F = \pm 10 \text{ mA}, V_{CE} = 10 \text{ V}$ | CTR_{CE} | H11AA4 | 100 | | | % |
| | | | H11AA3 | 50 | | | |
| | | | H11AA1 | 20 | | | |
| | | | H11AA2 | 10 | | | |
| Current Transfer Ratio, Symmetry | $I_F = \pm 10 \text{ mA}, V_{CE} = 10 \text{ V}$ (Figure.8) | | All | .33 | | 3.0 | % |
| Saturation Voltage Collector to Emitter | $I_F = \pm 10 \text{ mA}, I_{CE} = 0.5 \text{ mA}$ | $V_{CE(SAT)}$ | All | | | .40 | V |

ISOLATION CHARACTERISTICS

| Characteristic | Test Conditions | Symbol | Min | Typ | Max | Units |
|----------------------------------|---|-----------|-----------|-----|-----|----------|
| Package Capacitance input/output | $V_{I-O} = 0, f = 1 \text{ MHz}$ | C_{I-O} | | 0.7 | | pF |
| Isolation Voltage | $f = 60 \text{ Hz}, t = 1 \text{ min.}$ | V_{ISO} | 5300 | | | V |
| Isolation Resistance | $V_{I-O} = 500 \text{ VDC}$ | R_{ISO} | 10^{11} | | | Ω |

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Fig. 1 Input Voltage vs. Input Current

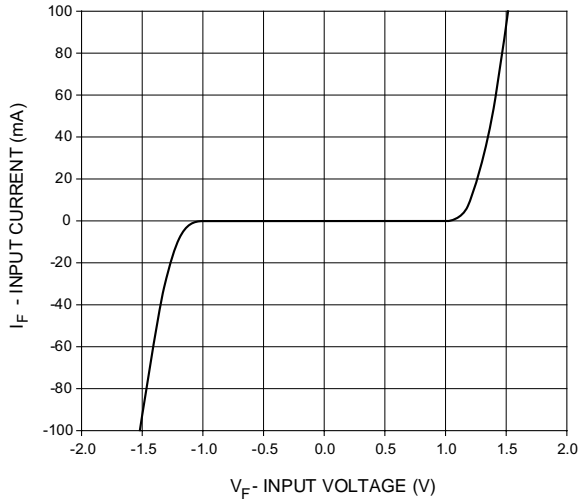


Fig. 2 Normalized CTR vs. Forward Current

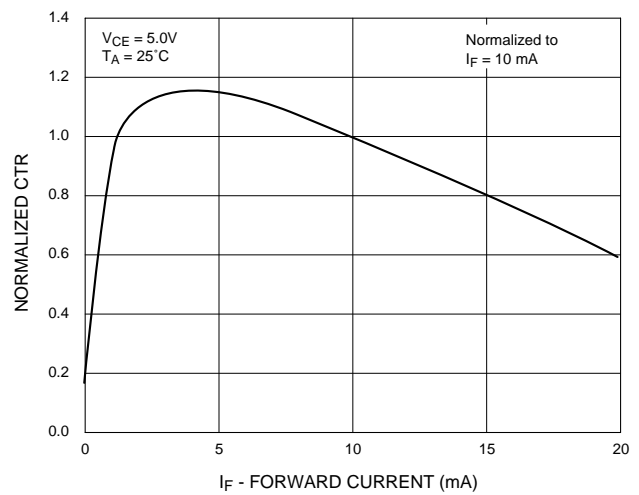


Fig. 3 Normalized CTR vs. Ambient Temperature

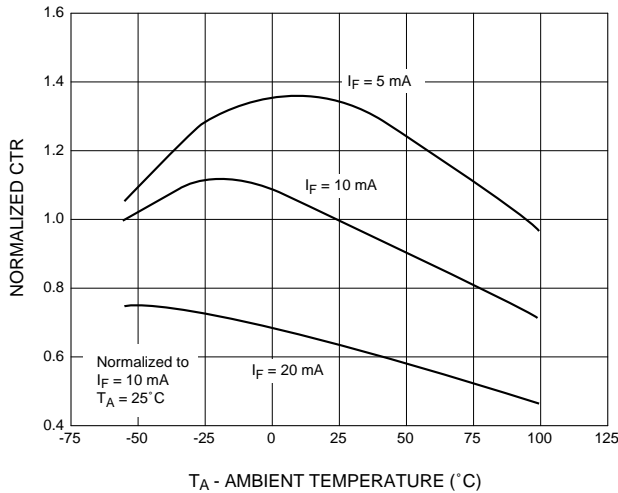


Fig. 4 CTR vs. R_BE (Unsaturated)

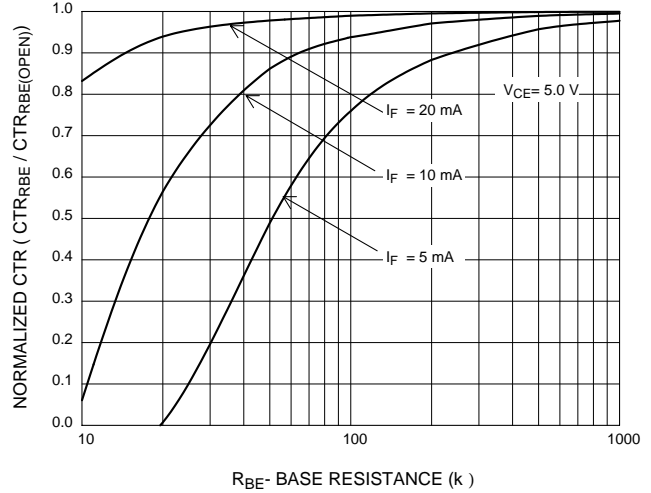


Fig. 5 CTR vs. R_BE (Saturated)

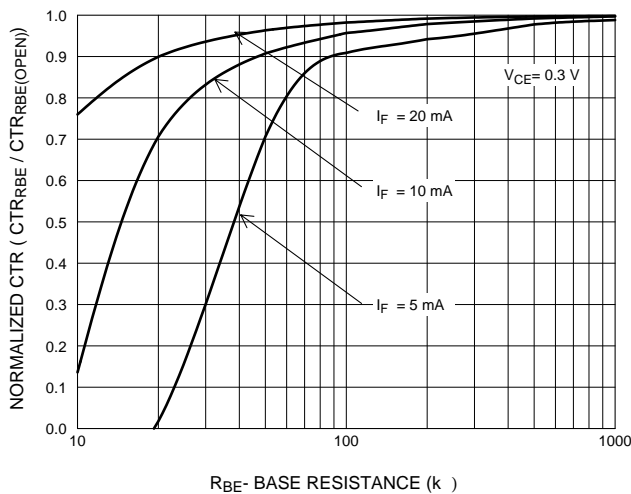
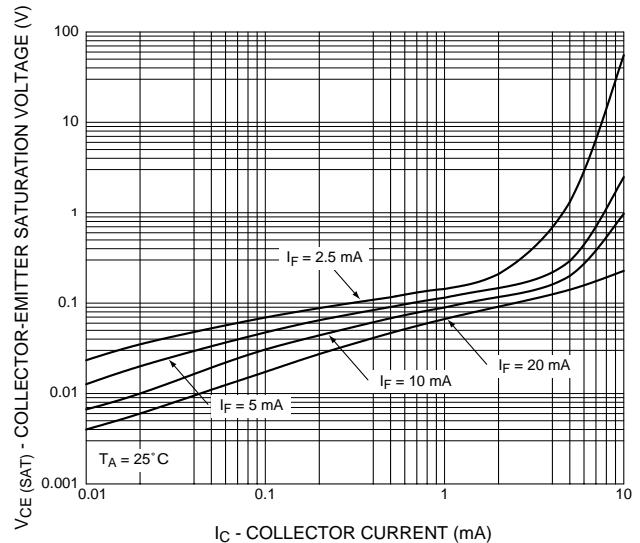


Fig. 6 Collector-Emitter Saturation Voltage vs Collector Current



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Fig. 7 Switching Speed vs. Load Resistor

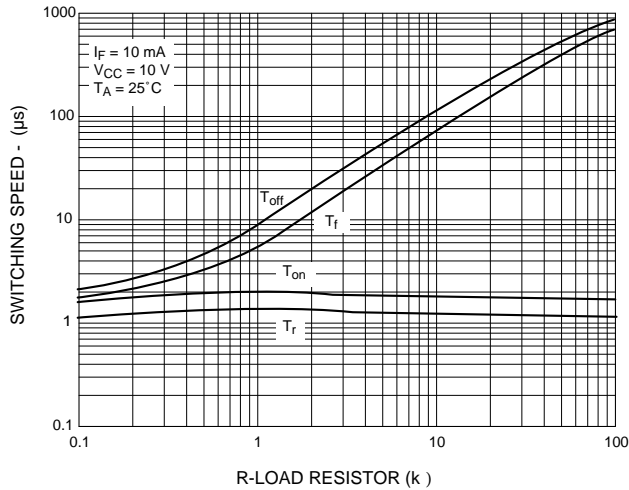


Fig. 8 Normalized t_{on} vs. R_{BE}

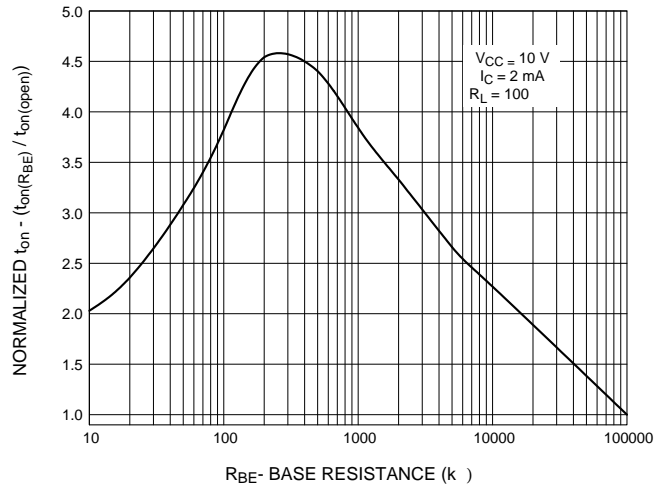


Fig. 9 Normalized t_{off} vs. R_{BE}

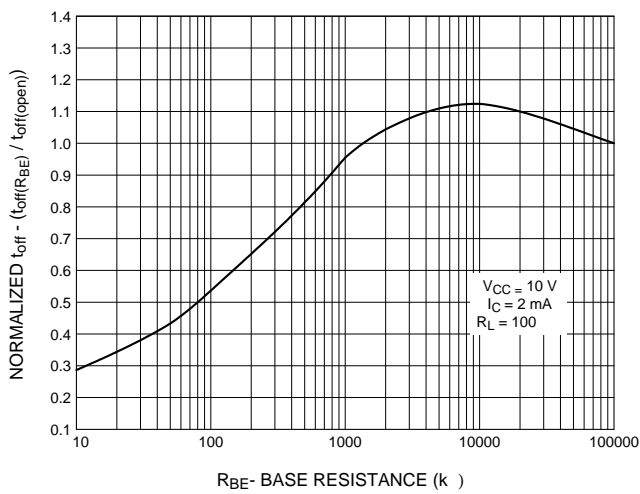


Fig. 10 Dark Current vs. Ambient Temperature

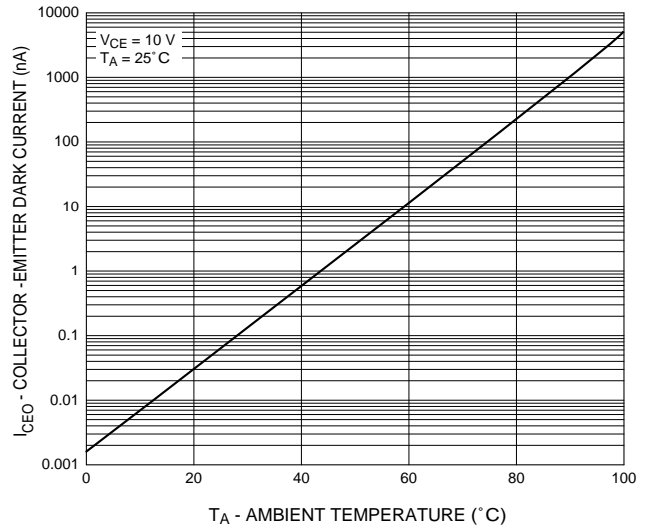
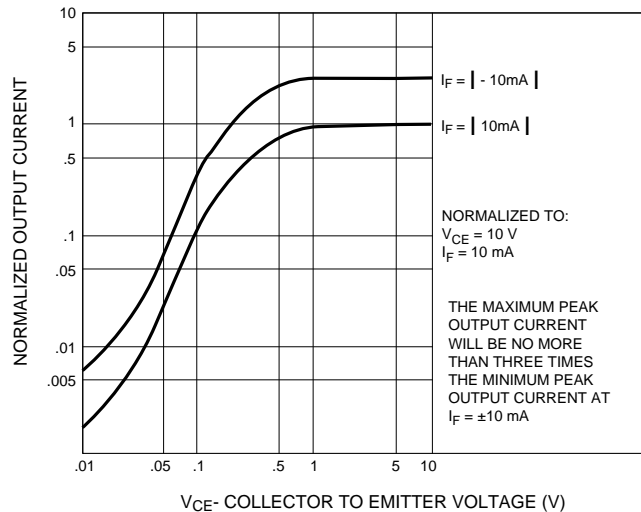


Fig. 11 Output Symmetry Characteristics



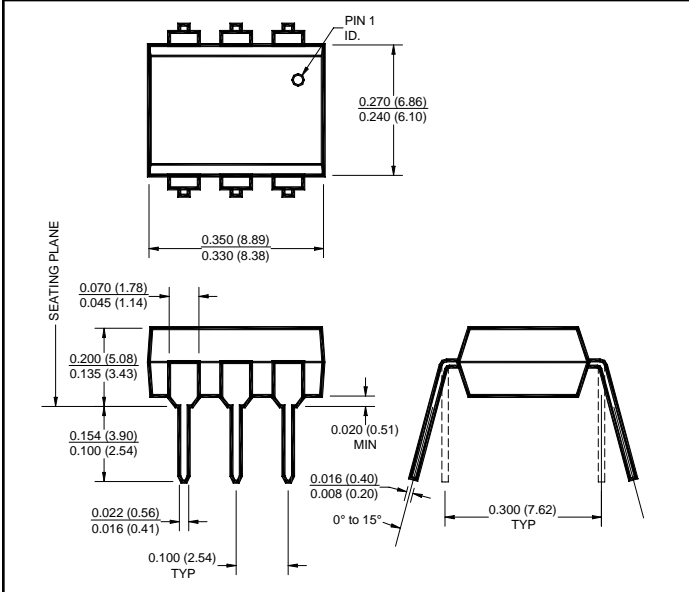
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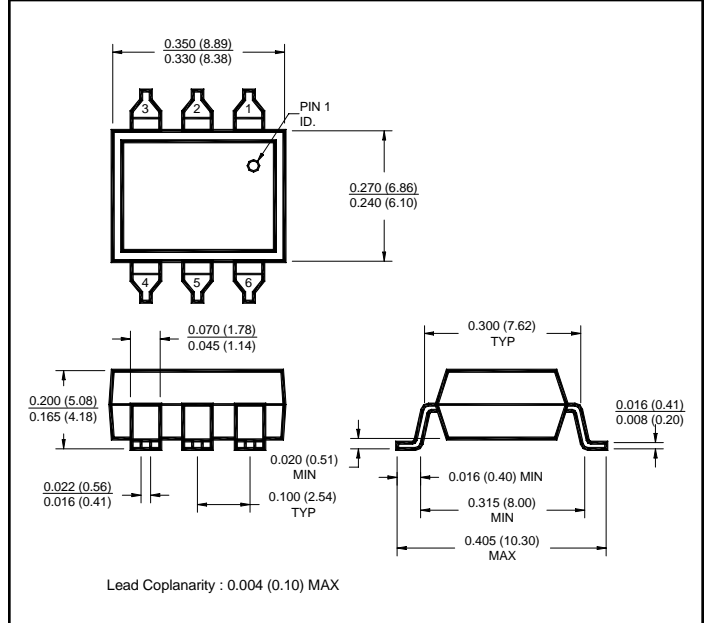
H11AA2

H11AA4

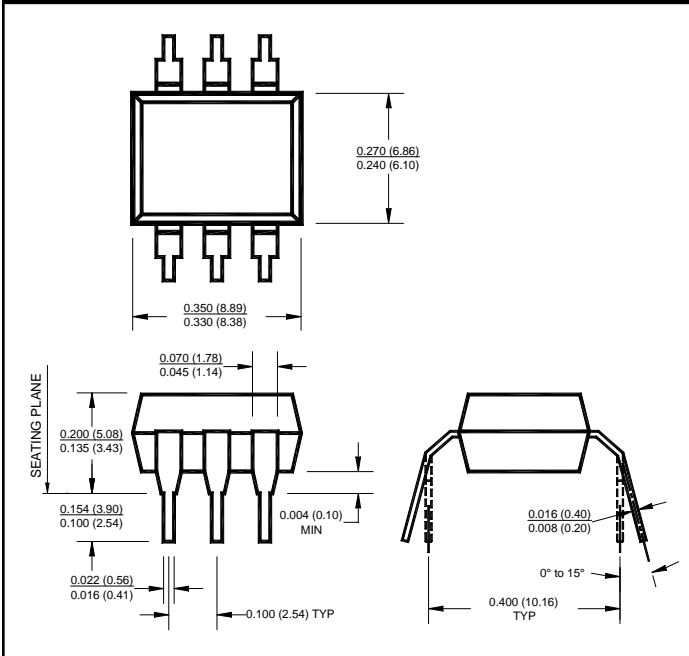
Package Dimensions (Through Hole)



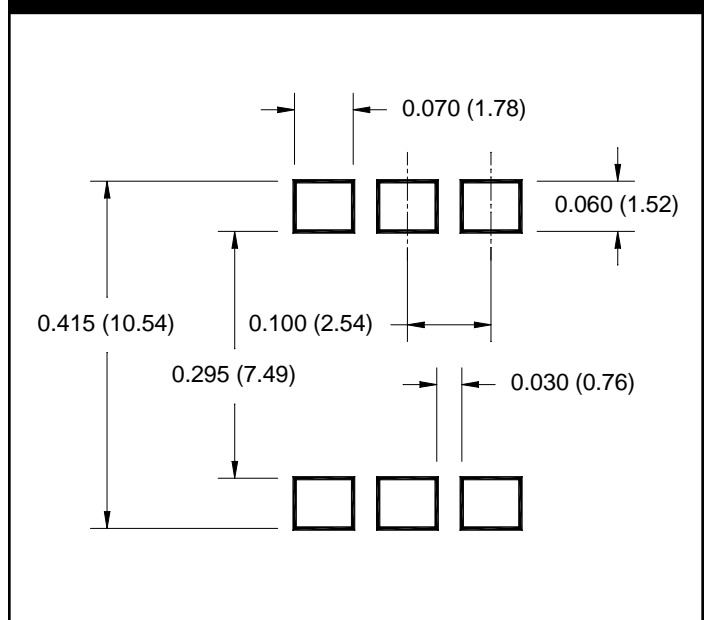
Package Dimensions (Surface Mount)



Package Dimensions (0.4" Lead Spacing)



**Recommended Pad Layout for
Surface Mount Leadform**



NOTE

All dimensions are in inches (millimeters)

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H11AA3

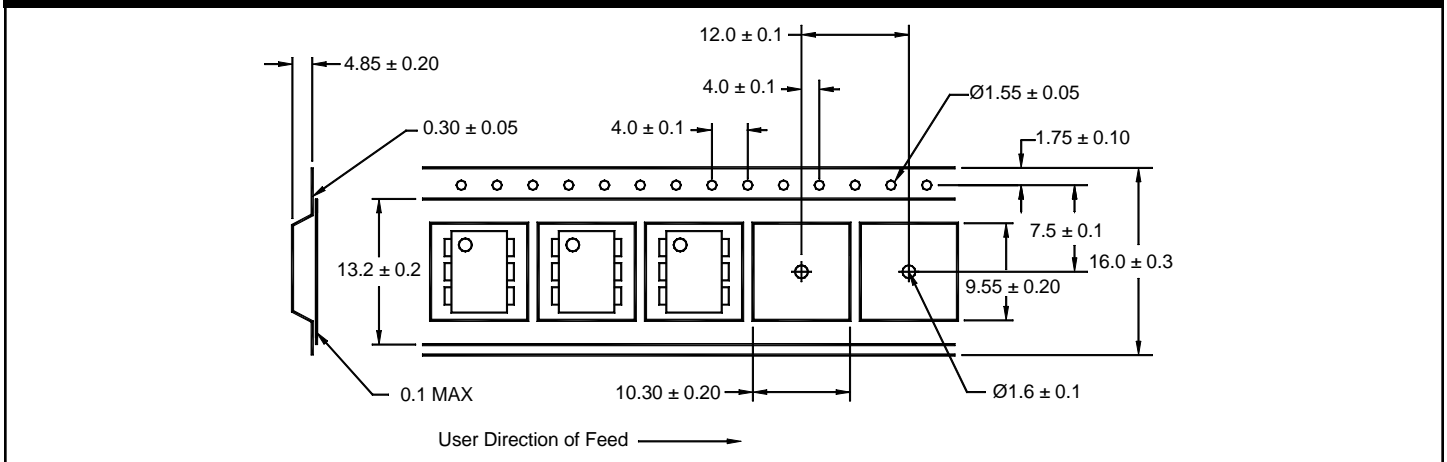
H11AA2

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ORDERING INFORMATION

| Option | Order Entry Identifier | Description |
|--------|------------------------|--|
| S | .S | Surface Mount Lead Bend |
| SD | .SD | Surface Mount; Tape and Reel |
| W | .W | 0.4" Lead Spacing |
| 300 | .300 | VDE 0884 |
| 300W | .300W | VDE 0884, 0.4" Lead Spacing |
| 3S | .3S | VDE 0884, Surface Mount |
| 3SD | .3SD | VDE 0884, Surface Mount, Tape and Reel |

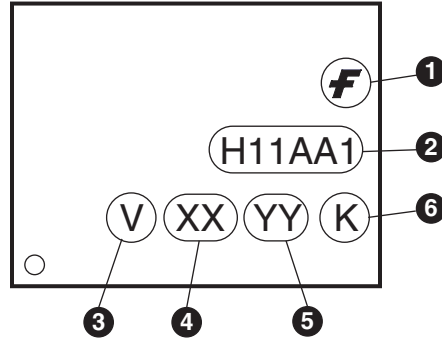
Carrier Tape Specifications ("D" Taping Orientation)



NOTE

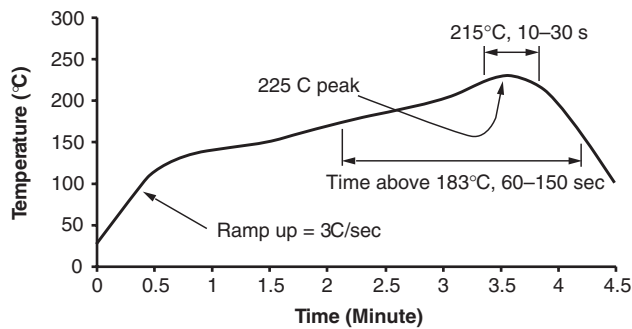
All dimensions are millimeters

MARKING INFORMATION



| Definitions | |
|-------------|--|
| 1 | Fairchild logo |
| 2 | Device number |
| 3 | VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table) |
| 4 | Two digit year code, e.g., '03' |
| 5 | Two digit work week ranging from '01' to '53' |
| 6 | Assembly package code |

Reflow Profile (Black Package, No Suffix)



- Peak reflow temperature: 225°C (package surface temperature)
- Time of temperature higher than 183°C for 60–150 seconds
- One time soldering reflow is recommended

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PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|------------------------|---|
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